

L Number	Hits	Search Text	DB	Time stamp
1	7	"6037588" or "5953579"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:25
8	1	("6037588" or "5953579") and (ground\$3 or ((detect\$5 or measur\$5) with current))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:28
15	1	("6037588" or "5953579") and (ground\$3 or ((absorb\$5 or adsorp\$5 or detect\$5 or measur\$5) with current))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:29
22	1	("6037588" or "5953579") and ground\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:31
29	7621	((250/306,307,309,311,492.2) or (438/16)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:34
36	5017	((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:06
43	3503	((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:06
50	1696	((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:39
57	753	((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:40
64	597	((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:16

71	433	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:42
78	141	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:43
85	83	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current) and ground\$4 and display\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:44
92	80	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current) and ground\$4 and display\$4 and (scan\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:46
93	77	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current) and ground\$4 and display\$4 and (scan\$6)) and (tim\$4 or period)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:47

94	14	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current) and ground\$4) and display\$4) and (scan\$6)) and (tim\$4 or period)) and ((multiple or plural\$4 or number) with (hole or via\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:49
101	14	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current) and ground\$4) and display\$4) and (scan\$6)) and (tim\$4 or period)) and ((multiple or plural\$4 or number) with (hole or via\$1))) and (region or section or area or sector\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:51
108	5	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and (hole or via\$1)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (hole or via\$1))) and (electron or charged-particle or (charged adj particle))) and current) and ground\$4) and display\$4) and (scan\$6)) and (tim\$4 or period)) and ((multiple or plural\$4 or number) with (hole or via\$1))) and (region or section or area or sector\$2)) and depth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:06
115	316	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen) with (hole or via\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:11
122	218	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen) with (hole or via\$1))) and method and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample) with (hole or via\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:12

129	59	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen) with (hole or via\$1))) and method and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample) with (hole or via\$1))) and current and ground\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:14
136	53	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen) with (hole or via\$1))) and method and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample) with (hole or via\$1))) and current and ground\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:13
143	9	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen) with (hole or via\$1))) and method and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample) with (hole or via\$1))) and current and ground\$3) and imag\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:15
150	7	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen) with (hole or via\$1))) and method and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample) with (hole or via\$1))) and current and ground\$3) and (current with ground\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:15
157	6	(((((250/306,307,309,311,492.2) or (438/16)).CCLS.) and (inspect\$5 or detect\$5 or examin\$5 or measur\$6)) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen or hole or via\$1))) and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample or specimen) with (hole or via\$1))) and method and ((inspect\$5 or detect\$5 or examin\$5 or measur\$6) with (semiconductor or wafer or sample) with (hole or via\$1))) and current and ground\$3) and imag\$5) and (current with ground\$3)) and (electron or charged-particle or (charged adj particle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:16

6 ((((((((((250/306,307,309,311,492.2) or
(438/16)).CCLS.) and (inspect\$5 or
detect\$5 or examin\$5 or measur\$6)) and
(((inspect\$5 or detect\$5 or examin\$5 or
measur\$6) with (semiconductor or wafer or
sample or specimen or hole or via\$1))) and
(((inspect\$5 or detect\$5 or examin\$5 or
measur\$6) with (semiconductor or wafer or
sample or specimen) with (hole or via\$1)))
and method and (((inspect\$5 or detect\$5 or
examin\$5 or measur\$6) with (semiconductor
or wafer or sample) with (hole or via\$1)))
and current and ground\$3) and imag\$5) and
(current with ground\$3)) and (electron or
charged-particle or (charged adj
particle))) and (display\$4 or monitor\$4 or
screen)

USPAT;
US-PGPUB;
EPO; JPO;
DERWENT;
IBM_TDB

2003/03/18 14:17